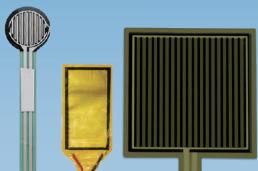
Tactilus FREE FORM® Sensor System

Now with a higher temperature range, up to 200°C!



The Tactilus® free form sensor system is a "user constructed"

tactile surface pressure system that provides unprecedented

flexibility and ease of use. The free form philosophy is to

empower the user to select the precise location where they

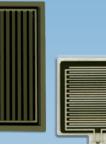
require data collection rather than the constrained "matrix"

Designed for multi-axis or curvaceous topographies the

Tactilus® Free Form sensor system provides engineers the capability to collect and assimilate data from up to

32 separate sensor elements simultaneously, at desired

inherent in traditional fixed surface sensor skins.











Unique to the industry, each Free Form sensor element is individually calibrated, sequentially serialized and quality tested to ensure the highest repeatability and accuracy. In addition, our sensor assemblies feature ergonomic and high quality Berg connectors, ensuring durable interconnection.

locations on an application surface to maximize data

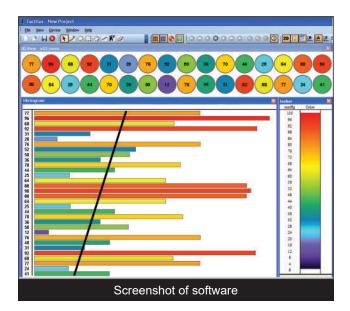
collection efficiency and value. This new approach to

constructing their own sensor "matrix."

tactile surface pressure mapping maintains data integrity

and usefulness while allowing engineers the capability of

Single Sensing Point





Our high precision free form sensors are accurate to an unprecedented ± 5%!

SENSOR SPECIFICATIONS	
Technology	Resistive
Pressure Range	0 - 400 PSI (0 - 28.1 kg/cm²)
Dimensions	From 3 mm to 44 mm diameter
Thickness	14 mils or thinner
Durability	Up to 1 million cycles
Recommend Current	5 mA
Supply Voltage	3-6 VDC
Temperature Range	0° to 200°F (0° to 93°C)
Scan Speed	Up to 1,000 hertz
Repeatability	< ±10% of calibrated range*
Hysteresis	< 10% of calibrated range
Drift	< 10% per log (time scale)

System includes: sensor elements, electronic controller, software and cables *HP (high precision) Free Form sensors can characterize pressure at +-5%

COMMON APPLICATIONS



Aerospace: composite bonding, nip pressures



Automotive: door seals, impact forces, fuel cells



Electronics: heat sink analyisis, nip pressures, lamination, LCD bonding



Factory: lamination, clamping, heat sealing, nip pressures



Orthopedics: joint analysis, ergonomics